KMB14F THRU KMB120F

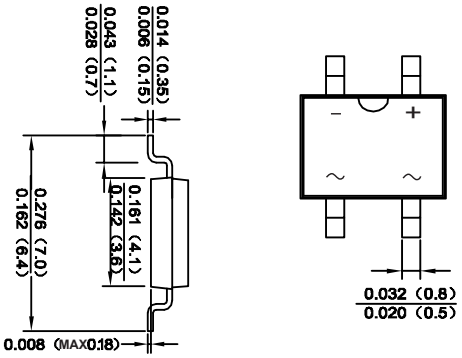
Voltage Range - 40 to 200 V olts Forward Current - 1.0 Ampere

Schottky Surface Mount Flat Bridge Rectifier

Features

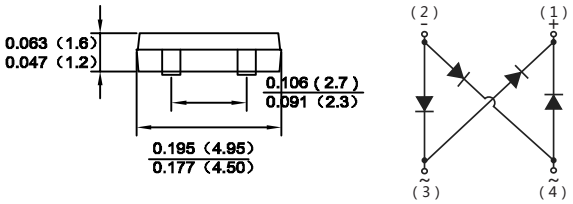
MBF

- Surge overload rating: 30 amperes peak
- Ideal for printed circuit board
- Plastic material has Underwriters Laboratory Flammability Classification 94V-0
- Low leakage
- Reliable low cost construction utilizing molded



Mechanical Data

Case : JEDEC MBF Molded plastic body
Terminals : Solder plated, solderable per MIL-STD-750,Method 2026
Polarity : Polarity symbol marking on body
Mounting Position : Any
Weight : 0.0026 ounce, 0.075 grams



Maximum Ratings And Electrical Characteristics

Dimensions in inches and (millimeters)

Ratings at 25°C ambient temperature unlss otherwise specified.

Single phase half-wave 60Hz,resistive or inductive load,for capacitive load current derate by 20%.

Parameter / Marking Code	SYMBOLS	MDD KMB14F	MDD KMB16F	MDD KMB18F	MDD KMB110F	MDD KMB115F	MDD KMB120F	UNITS
Maximum repetitive peak reverse voltage	V_{RRM}	40	60	80	100	150	200	V
Maximum RMS voltage	V_{RMS}	28	42	56	70	105	140	V
Maximum DC blocking voltage	V_{DC}	40	60	80	100	150	200	V
Maximum average forward rectified current	$I_{F(AV)}$	1.0						A
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	30						A
Maximum instantaneous forward voltage per at 1A	V_F	0.55	0.70	0.85		0.90		V
Maximum DC reverse current T_A=25°C at rated DC blocking voltage T_A=100°C	I_R	0.3 10		0.2 5		0.1 2		mA
Typical thermal resistance (NOTE1)	$R\theta_{JA}$ $R\theta_{JL}$	100 20						°C/W
Typical junction capacitance	C_j	110	80					pF
Operating temperature range	T_J	-55 to +125						°C
storage temperature range	T_{STG}	-55 to +150						°C

Note：1.Thermal resistance from junction to ambient and from junction to lead P.C.B.mounted on 0.2×0.2"(5.0×5.0mm)copper pad areas.

Ratings And Characteristic Curves

Fig.1 Forward Current Derating Curve

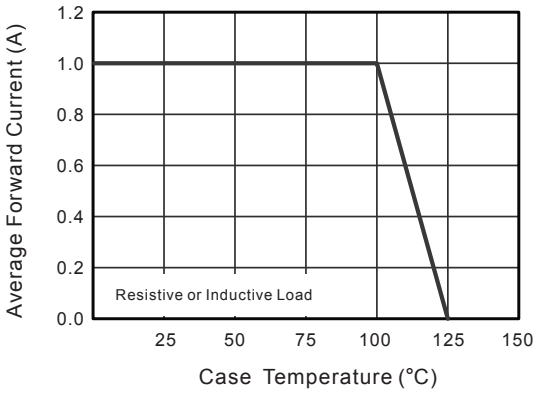


Fig.2 Typical Reverse Characteristics

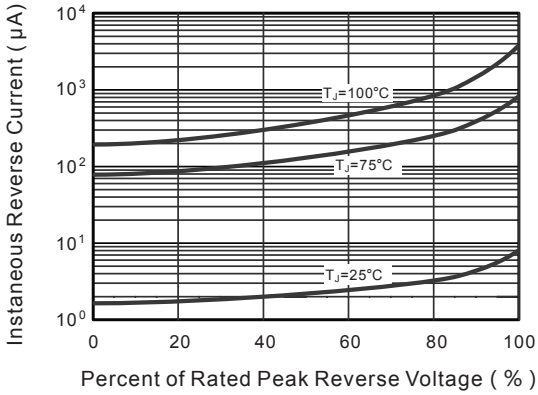


Fig.3 Typical Forward Characteristic

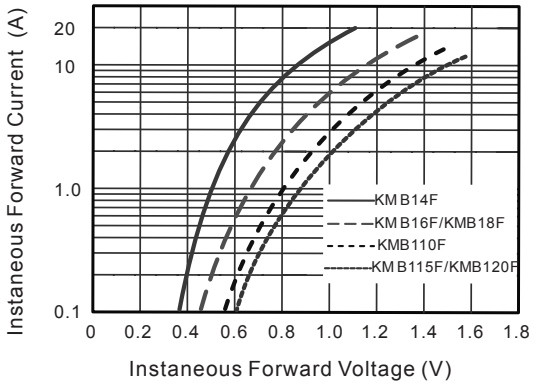


Fig.4 Typical Junction Capacitance

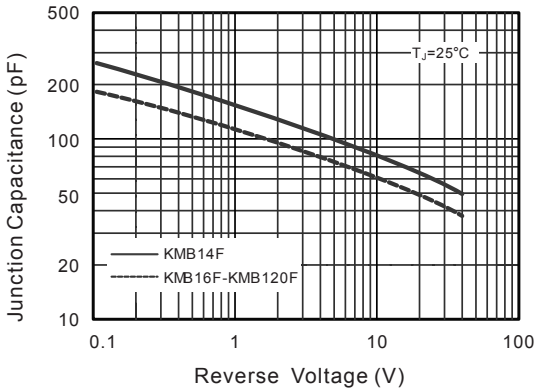


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current

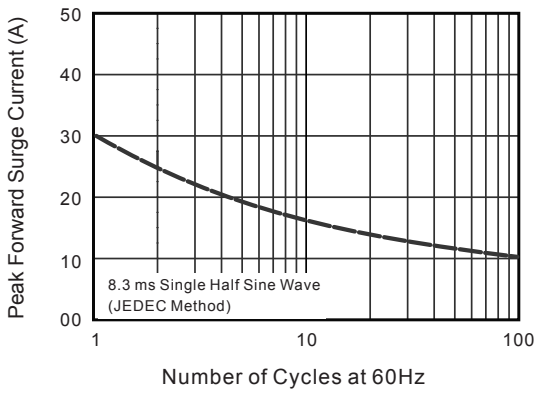
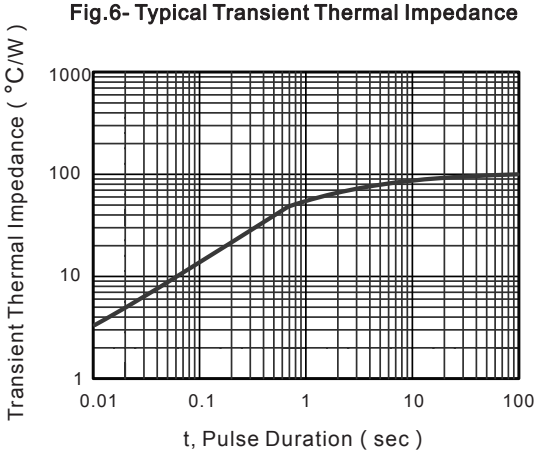
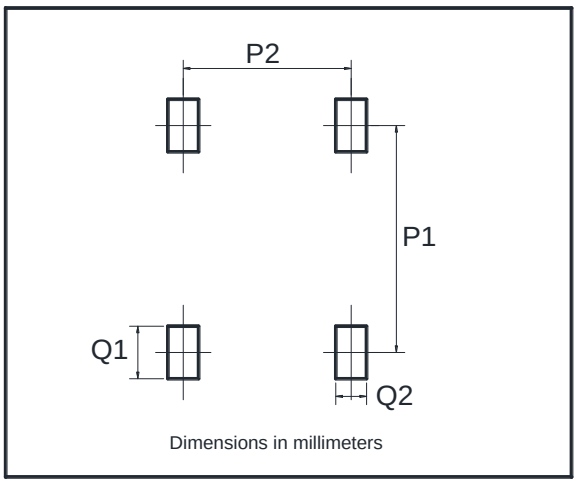


Fig.6- Typical Transient Thermal Impedance



The curve above is for reference only.

Suggested Pad Layout



Dim	Min
P1	6.00
P2	2.40
Q1	1.84
Q2	1.20

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